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FormFactor Announces New Single Spring Repair Capability for Memory Probe Cards

Rapid Repair Service Improves Uptime at Wafer Probe

LIVERMORE, Calif.--Feb. 9, 2004--FormFactor, Inc. (Nasdaq:FORM - News), a leading provider of advanced wafer probe cards, today announced the company has extended individual MicroSpring® contact repair capability to all of FormFactor's memory probe cards, improving the availability of probing resources for memory semiconductor manufacturers. The new repair capability is the latest addition to FormFactor's High Availability Services (HAS) Program, which is designed to increase productivity in the test cell by offering faster replacement and repair turnaround times. Aggressive memory device cost reduction goals are driving semiconductor manufacturers to optimize every aspect of the test process to reduce unproductive test cell downtime. In the highly competitive DRAM industry, FormFactor's cost of test models indicate that a semiconductor manufacturer's loss of even one percent of test cell availability can result in substantial lost revenue shipments per year.

FormFactor's individual spring repair capability reduces advanced probe card repair time to as little as 24 hours, significantly reducing test cell downtime due to probe card failure. The new spring repair capability drives down the cost of servicing FormFactor's advanced probe cards without compromising performance. Based on extensive field trials and internal qualification, repaired springs provide performance and reliability functionally equivalent to that of the advanced probe card's original springs. This capability enhances FormFactor's established reputation for superior service and reliability, and enables manufacturers to further reduce the already low total cost of ownership of FormFactor products.

"FormFactor's advanced probe cards are known for their durability and robustness. However, when repairs are necessary our individual spring repair capabilities allow us to improve test cell utilization for our memory customers, enabling them to quickly resume production," said Stefan Zschiegner, senior director of FormFactor's Solutions and Support group. "This new solution is part of FormFactor's High Availability Services Program, which allows customers to choose support products that deliver up to 99 percent availability to ensure critical production volume milestones are met."

FormFactor's Solutions and Support Group operates a worldwide network of on-site support teams and regional service centers to provide ongoing support of the large installed base of the company's wafer test products. The HAS program's comprehensive menu of options includes replacement service in less than 24 hours and probe card repair times as short as four days. More information about FormFactor products can be found on the Web at www.formfactor.com.

About FormFactor

FormFactor, Inc. (Nasdaq:FORM - News) is an industry leader in the design, development, manufacture, sale and support of precision, high-performance advanced semiconductor wafer probe cards. The company's products are based on its proprietary MicroSpring® interconnect technology and proprietary design processes, which enable FormFactor to produce wafer probe cards for test applications that require reliability, speed, precision and signal integrity. FormFactor is headquartered in Livermore, California. For more information, visit the company's web site at www.formfactor.com.

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Forward-Looking Statements

Statements in this press release that are not strictly historical in nature are forward-looking statements within the meaning of the federal securities laws. These statements are based on current information and expectations that are inherently subject to change and involve a number of risks and uncertainties. These statements should not be read as predictions or projections of future performance. Actual events or results might differ materially from those in any forward-looking statement due to various factors, including, but not limited to: the demand for certain semiconductor devices; the performance and market acceptance of the Company's new products, programs (including the High Availability Services Program) or technologies; the implementation of volume production of the Company's new products; changes in semiconductor manufacturers' test strategies, equipments or processes; and the Company's relationships with customers and companies that manufacture semiconductor test equipment. Additional information concerning factors that could cause actual events or results to differ materially from those in any forward looking statement is contained in the Company's latest Form 10-Q filed with the Securities and Exchange Commission ("SEC") and subsequent SEC filings made by the Company. Copies of filings made by the Company with the SEC are available at <http://investors.formfactor.com/edgar.cfm>. The Company assumes no obligation to update the information in this press release, to revise any forward-looking statements or to update the reasons actual results could differ materially from those anticipated in forward-looking statements.